

AAEON Embedded Solutions

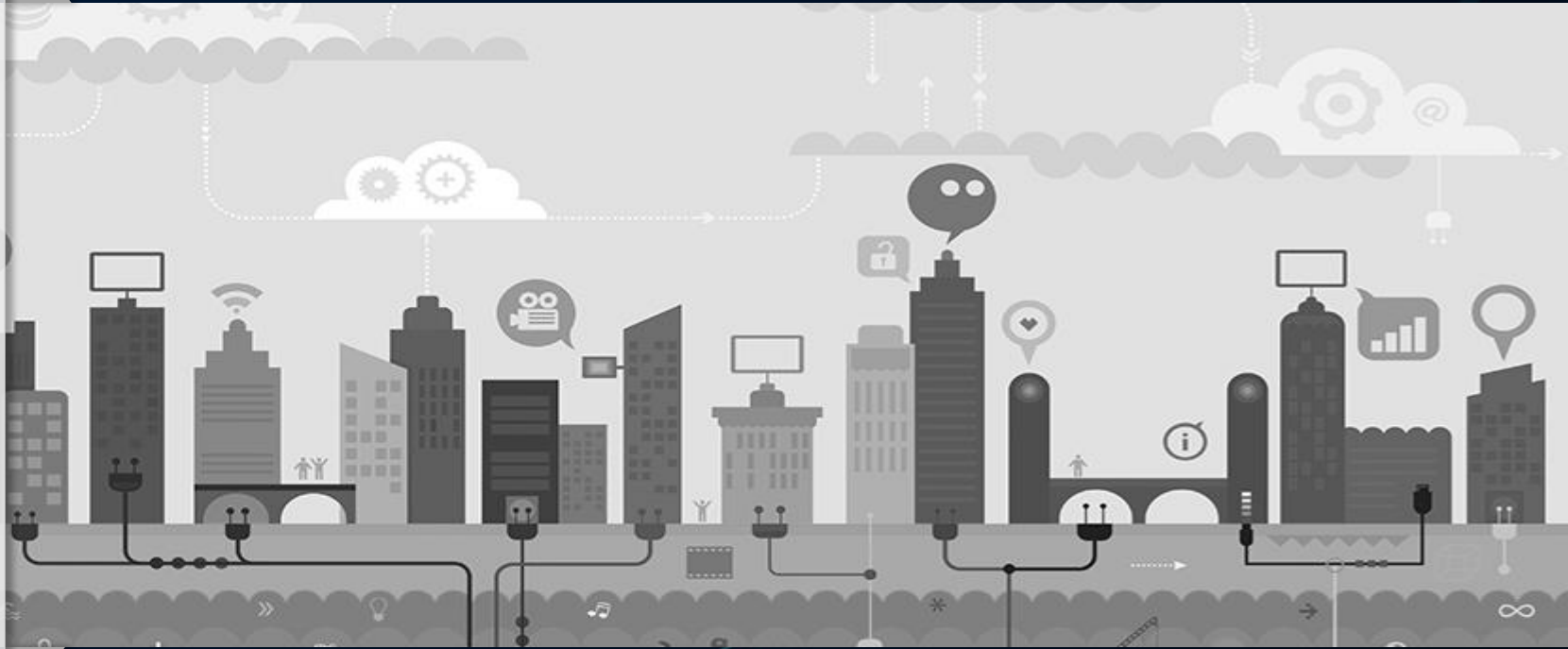
Embedded World 2022



Hall 1, Booth 306

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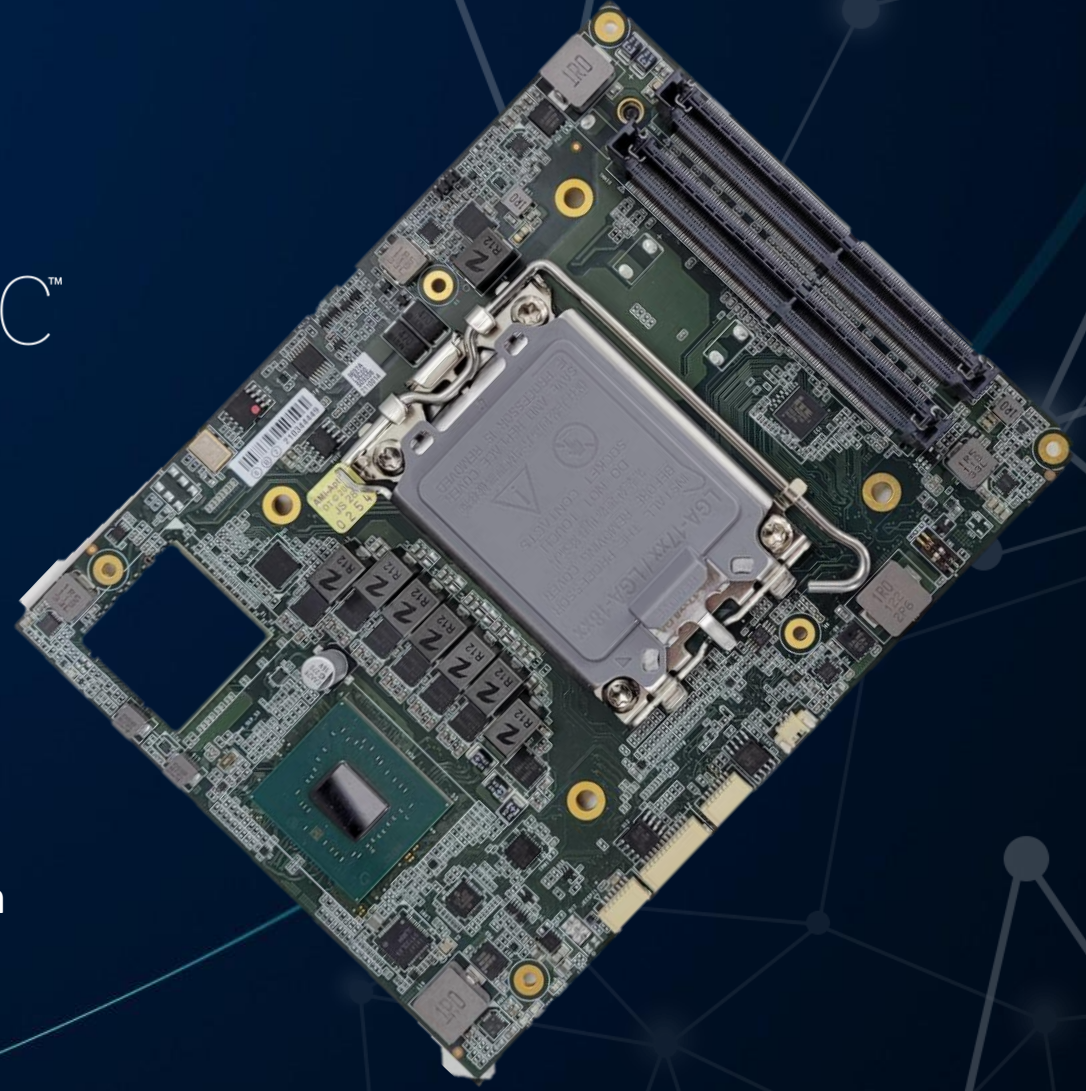


Smaller, Faster, and Stronger Solutions with AAEON's Computer-on-Modules

Providing High-Performance Computing in a Globally Connected World

HPC -ADSC COM+HPC™

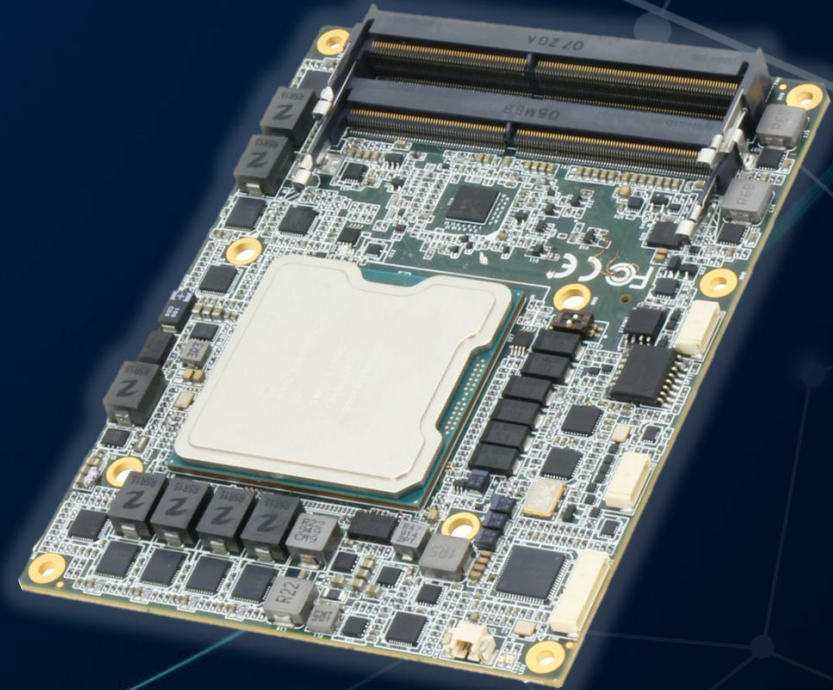
- Intel® 12th-Gen Alderlake-S + R680E PCH
- CPU TDP up to 95W (16C/24T)
- DDR5 SODIMM x 2 , up to 128GB (ECC Support)
- 2.5GbE x1, 25GbE x 1
- PCIe x16 Gen 5, PCIe x4 Gen 4, PCIe x1 Gen 3
- M.2 NVMe [x2]
- COM-HPC Standard, Client mode Size C 120mm x 160mm



COM-ICDB7

COM
Express®

- Intel® SoC XEON® D LCC Series
- CPU TDP up to 70W (10C/20T)
- DDR4 SODIMM x 4 , up to 128GB (ECC Support)
- 10 GbE x 4 , GbE x 1
- PCIe x16 Gen 4 and PCIe Gen 3
- COMe Type 7, 125mm x 95 mm
- Operation Temp: 0 ~ + 60 C



COM-TGUC6



- Intel® 11th Gen Core-i Tigerlake-UP3 SoC
- DDR4 SODIMM x 2 (up to 64GB)
- VGA, DDI x 3, LVDS/eDP x 1
- 2.5 GbE x 1
- PCIe Gen3 [x1] x 5, PEG [x4] x 1 (Gen4)
- COMe Type 6, Compact size 95mm x 95 mm
- Operation Temp: -40 ~ +85C (Industrial SKU)

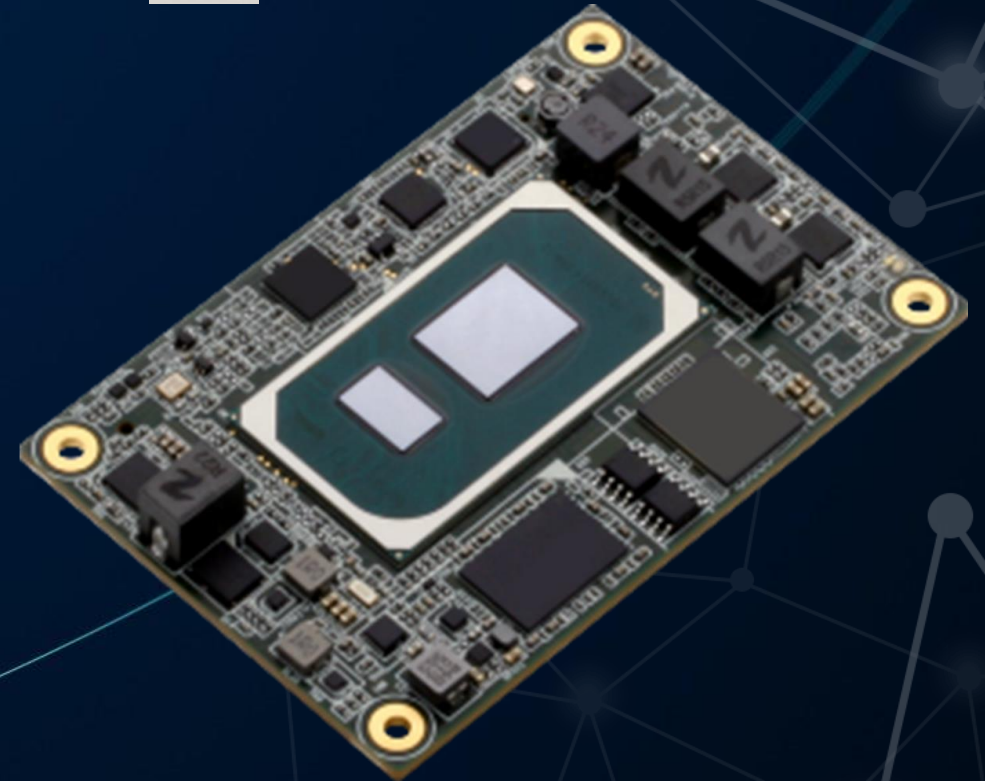


NanoCOM-TGU

COM
Express®



- Intel® 11th Gen Core-i Tigerlake-UP3 SoC
- Onboard LPDDR4x 16GB, NVMe up to 512GB
- DDI x 1, eDP x 1
- 2.5 GbE x 1
- PCIe Gen4 [x1] x 4
- COMe Type 10, 84mm x 55 mm
- Operation Temp: -40 ~ +85C (Industrial SKU)



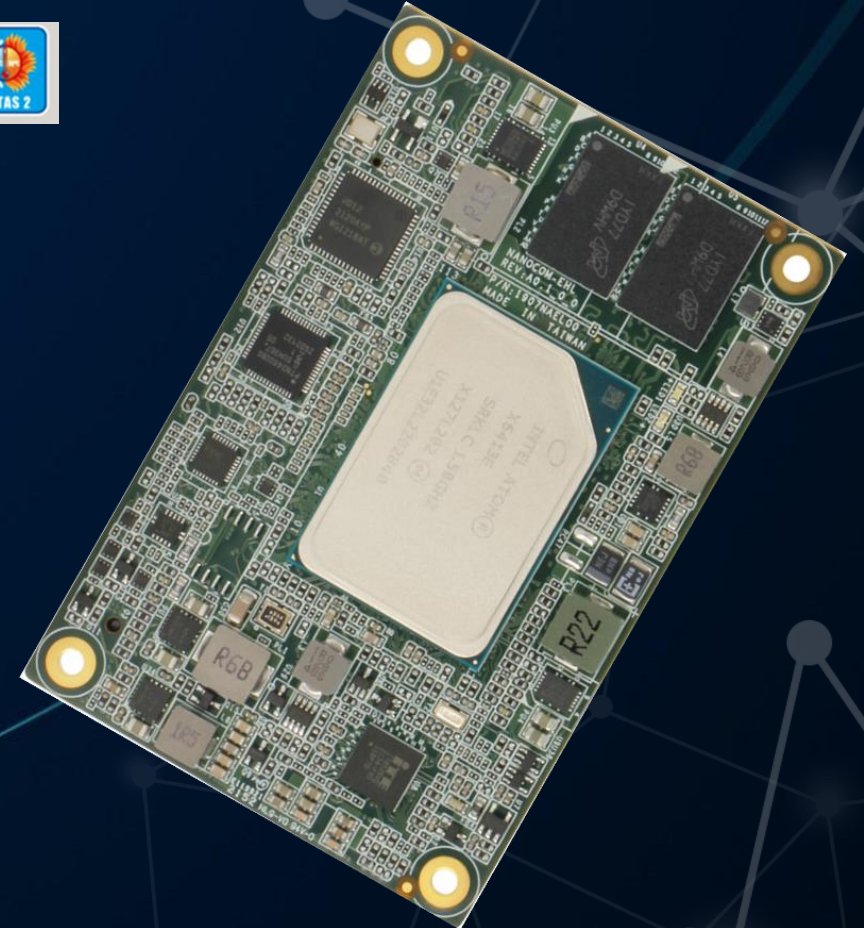
NanoCOM-EHL

**COM
Express®**



Est MP : Q3,2022

- Intel® Elkhart Lake X6000E Series
- Onboard LPDDR4x up to 16GB, eMMC up to 128GB
- DDI x 1, LVDS/ eDP x 1
- 2.5 GbE x 1
- PCIe Gen3 [x1] x 4
- COMe Type 10, 84mm x 55 mm
- Operation Temp: -40 ~ +85C (Selected SKU)



NVIDIA AI Solutions

Introducing the world to unprecedented computing capabilities for edge AI with NVIDIA

BOXER-8251AI

- NVIDIA® Jetson Xavier™ NX
- AI@Edge Compact Fanless Embedded Box PC
- 8GB LPDDR4x
- 16GB onboard eMMC
- USB3.2 Gen 1 x 4
- LAN x 1 + RS-232 x 2
- 12Vdc Power input



BOXER-8253AI

- NVIDIA® Jetson Xavier™ NX
- 6 Core ARM® Carmel® V8.2 64bit CPU
- 8 GB RAM, 16GB eMMC
- Allxon swiftDR OOB Enabler (hardware module)



BOXER-8255AI

- NVIDIA® Jetson Xavier™ NX
- LPDDR4 8GB, eMMC 16 GB/mSATA/SATA support
- GMSL2 x6 Camera with Fakra Connectors
- CANBUS x2, DI0 x6 Channel
- WiFi/4G/5G/GPS connectivity
- Pre-installed NVIDIA Jetpack SDK
- 9~40Vdc with 2-pin terminal block
- Support vehicle protection/ACC/Ignition
- Operating temperature -20°C ~ 65 °C



BOXER-8256AI

- NVIDIA® Jetson Xavier™ NX
- 8GB 128-bit LPDDR4x
- 16GB eMMC 5.1
- HDMI Type A x 2 for HDMI 2.0
- USB Type A x 1 for USB 3.2 Gen 1 x3
- DB9 for RS-232/422/485*1+ CANBUS x1
- RJ-45 x 1 for GbE LAN
- Audio x 1 (Mic-in/Line-Out)
- 12~24Vdc with 2-pin terminal block

**COMING
SOON**

BOXER-8640AI

- NVIDIA® AGX Orin™
- 1792-core Ampere GPU with Tensor cores
- Support RJ-45 x 4 for PoE (802.11af, total 60W)
- Support DB-9 x 1 for RS-232/422/485, CANBUS x 1
- Support 40-pin header, Mic in and Line out
- Support M.2 E key, M key and SATA storage



Intel Edge Computing Systems

Bringing the power of AI and Edge Computing to Industrial and Embedded Applications

BOXER-6645-ADS

- 12th Generation Intel® Desktop Processor
- Built-in high performance Intel Iris Xe Graphic Engine
- Dual-Channel DDR5 SODIMM, Total max. 64GB
- Support Quadruple Independent Display (HDMI x2, DP x2)
- Support SuperSpeed+ USB 3.2 Gen2 x8 (A2)
- Support M.2 3052 w/ USB3.2 (5G) for 5G module
- Support Quadruple LAN (GbE x3, 2.5GbE x1), vPRO and iAMT
- Support Windows 11, TPM, DirectX 12

**COMING
SOON**

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partner
Titanium



UP Xtreme i11

EdgeCompute Enabling Kit

- 11th Gen Intel[®] Core[™] i7/i5/i3/Celeron[®] Processor SoC (formerly Tiger Lake UP3)
- DDR4 SO-DIMM Slot x 2 (up to 64GB)
- 16pin GPIO connector x1
- SATA storage
- Ready to connect 5G, WiFi (WiFi 5/WiFi 6), Bluetooth
- Support LAN up to 2.5Gbps
- Fanless/Fan design available
- Ubuntu 20.04



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UP Squared 6000

Edge Computing Kit

- Intel® Atom® x6000E Pentium® Celeron® Processor SoC
- Onboard LPDDR4 Memory up to 8GB
- Onboard eMMC Storage up to 64GB
- GbE x 1, 2.5GbE x 1 (Intel® i210, i225)
- USB 3.2 x3 (Type A x2, Type C x1)
- 40 pin GPIO x1
- DP 1.2 / HDMI 2.0b
- Multi-expansion capability: WiFi, 4G/ LTE, 5G, AI and Storage
- Ubuntu 20.04



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UP Squared Pro Edge

- Intel® Pentium® N4200/ Celeron® N3350/ Atom™ E3950 Processor SoC
- Onboard LPDDR4 Memory up to 8GB
- Onboard eMMC Storage up to 64GB
- Gigabit LAN x 2, USB 3.2 Gen 1 (Type A) x 3
- 12-24 VDC-in, 5A
- 16pin GPIO connector for 40 pin HAT



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EPIC-ADS7-PUC Series

- 12th Generation Intel® Core™ processor (formerly Alder Lake)
- 2x 8 or 16 GB DDR5 memory
- NVMe SSD 256 GB via M.2 2280
- 4x USB 3.2 Gen 2 Type A
- M.2 slots for expansion
- 1x HDMI, 2x DP++ (1.4a)



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IoT Gateway Systems

Implementing the IoT concept for various indoor and outdoor environments

SRG-APL

- Intel Atom® X5-E3940 Quad Core 1.6GHz
- Onboard LPDDR4 4 GB / eMMC 32G
- Built-in Micro SD Card Slot x 1
- Gigabit Ethernet RJ-45 x 2 LAN port
- M.2 E key x 1 (For Wifi/BT Module)
- Mini PCIe connector x 1 (For 4G LTE Module)
- CE-RED Certified



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SRG-IMX8P

- ARM NXP I.MX8M Plus Quad-Core Cortex A-53
- Memory: Onboard DDR4L 2GB (optional 4 GB)
- Storage: eMMC 16GB (Optional 32 GB)
- TPM 2.0
- Mini PCIe connector (for RF Module)
- Micro USB x1
- SIMcard slot x1 Micro SD slot x1
- Gigabit Ethernet x2, RJ-45
- CAN-FD x2 CH, Phoenix Connector

**COMING
SOON**

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Customization Service Center

Save time and resources by selecting or designing a pre-configured Turnkey Solution to suit the project requirements

GENESYS-TGU6/ADP6

Est MP : Q3,2022

- Intel 11th/ 12th Core-i Turnkey System
- DDR4 /5 SODIMM x 2 (up to 64GB)
- Multiple Digital output (HDMI/ DP)
- Intel 2.5 GbE x 1 + GbE x 1
- USB 3.2 Gen2 x 4 , USB-C x1
- M-key 2280 x1 , E-Key 2230 x 1, B-key 3052 x1 (ADP6)
- 12V / 9~36V DC input, 0-50 C (w/ FAN)



PICO-TGU4-SEMI

- Intel 12th Gen Core-i Turnkey System
- CPU TDP up to 28W
- Onboard LPDDR4x up to 32GB
- HDMI
- Intel 2.5 GbE x 1 + GbE x 1
- USB 3.2 Gen2 x 2 , COM x 2
- M-key 2280 x1 , mini-card x 1
- 12V DC-IN, 0-50 C (w/ FAN)



ACS-N200

Est MP : Q3,2022

- Intel 8th/9th Gen Core-i Turnkey System
- CPU TDP up to 65W
- DDR4 SODIMM x 2 (up to 32GB)
- VGA + HDMI
- Up to 4 x Intel GbE
- USB 3.2 Gen2 x 4 , USB 2.0 x 2
- M-key 2280 x1 (SATA only), E-Key 2230 x 1
- PCI x 16 Low Profile expansion
- Internal ATX PSU 250W, 0-40 C (w/ FAN)



ACS-15U01

Est MP : Q3,2022

- Intel 11th Core-i Turnkey System
- CPU TDP up to 28W
- DDR4 SODIMM x 2 (up to 64GB)
- DP x2 + HDMI x 2
- Intel 2.5GbE x 1 + Gigalan x 1
- USB 3.2 Gen2 x 2 , USB 2.0 x 4
- M-key 2280 x1, Mini-Card x 1
- 12V DC-IN, 0-50 C (w/ FAN)



Network Appliances

Deploy reliable network appliances around the globe with faster time-to-market and lower development costs

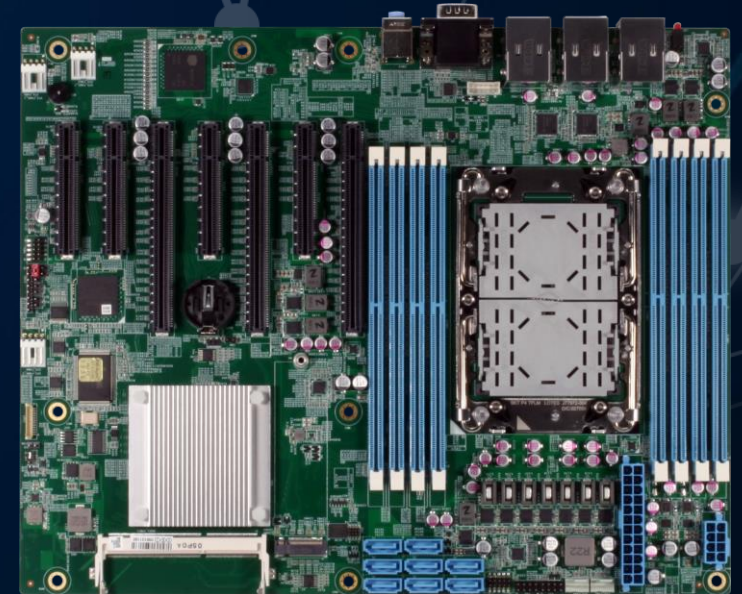
FWS-8600

- Dual 2nd Generation Intel® Xeon® Scalable processor
- 2U Rackmount Network Appliance
- Intel® C621 Chipset
- DDR4 2133/2400/2666 MHz RDIMM x 16, up to 512GB
- 1GbE RJ45 Intel® i211 x 2, NIM slot x 4 (Project based up to 8 slots)
- IPMI supported by AAEON Module
- External Hotswappable 3.5" HDD Bay x 4, Internal 3.5" HDD Bay x 1
- 550W ~ 600W Redundant Power

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ARES-WH10

- ATX Server Board
- Intel® Whitley Platform, Support Xeon® Single Ice Lake –SP CPU
- Intel® Communications Chipset C621A
- DDR4 2666 MHz R-DIMM Slot x 6
- SATA3 (6 Gbps) ports x 8; RAID 0,1,5,10
- M.2 M-Key 2280 with PCIe x 4 Signal
- Dual LAN with Intel® i210 Gigabit Ethernet Controller
- Audio In Out and VGA x 1



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UP Developer Platforms

Empowering Edge Computing with UP Industrial-Grade SBCs

UP Squared 6000 & Carrier Board



- Intel® Pentium® / Celeron® / Atom® x6000E Series
- Intel® UHD Graphics
- Intel® Programmable Services Engine (Intel® PSE)
- 40-pin HAT Connectors
- Supports WiFi 6E / BT/AI/5G via M.2 slots
- Dimension: 101.6 x 101.6 mm
- 12V DC-In
- Additional Carrier board:
 - 40-pin HAT and CANBus
 - Micro-USB (debug port PSE)
 - UART, RS232, mini MCle slot, and SIM slot
 - 2x Gigabit Ethernet



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UP Xtreme i11

UP
bridge
the gap

- 11th Generation Intel® Core mobile processors
- Intel® Iris® Xe Graphics, built in AI engine
- 2x SODIMM, up to 64GB RAM
- 40-pin HAT Connectors
- Support 4 independent Displays
- Support 5G module via M.2 3052 B key
- Support AI module via M.2 2280
- Support WiFi 6 via M.2 2230
- Support USB 4.0
- PCIe x 4 slot



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UP 4000 ^{UP}

bridge
the gap

- Intel® Pentium® N4200 / Celeron® N3350 / Atom® E3950
- Intel® Gen 9 HD Graphics
- Up to 8GB RAM/ Up to 64GB eMMC
- 40-pin HAT Connectors
- 3x USB 3.2 Gen 1 (Type A)
- 2x USB2.0 via wafer
- 1x HDMI 1.4b, 1x DP 1.2
- 12V DC-in



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UP Squared V2

bridge the gap

- Intel® Pentium® J6426 / Celeron® N6210
- Intel® UHD Graphics
- Up to 16GB RAM/ Up to 128GB eMMC
- 40-pin HAT Connectors
- 1x HDMI, 1x DP, 1x eDP
- Supports WiFi 6 / BT/ 5G via M.2 Slots
- Dimension: 85.6 x 90 mm
- 12V DC-in

**COMING
SOON**

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partner Titanium

UP Xtreme i12



- 12th Generation Intel® Core™ mobile processors
- Intel® Iris® Xe Graphics, built-in AI engine
- Up to 64GB LPDDR5 RAM
- 40-pin HAT Connectors
- 1x HDMI 2.0, 1x DP 1.4, 1x eDP. 1x DP via USB Type C
- 1x 1GbE, 1x 2.5GbE
- 1x Audio Jack (Mic in/Line out)
- Supports WiFi 6 / BT/ 5G via M.2 Slots
- Dimension: 120 x 120 mm
- 12~36V DC-in

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Spreading intelligence throughout a digital world

Contact: Marketing@aaeon.eu

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